such that after molding and curing of said resin, opening of both said top and centre mold plates causes a cull formed on said top face of said plunger to break off at said mold cavities and said cull retained on said top face of said plunger is readily removeable from said groove.

7. A transfer molding press according to claim 6, wherein said groove has a dovetail or C shape.

8. A transfer molding press according to claim 6, wherein said groove is tapered along said top face of said plunger.

9. A transfer molding press according to claim 6, wherein said top mold plate further comprises a corresponding number of mold cavities.

10. A method of transferring mold resin onto a substrate during a semiconductor encapsulation process with subsequent cull removal, said method comprising:

disposing a resin pellet into a pot sleeve and allowing said resin to melt, with said ~~resin~~ pot sleeve being disposed on a bottom mold plate and said pot sleeve having gates formed at a discharged end of said pot sleeve;

lowering a centre mold plate, on which is mounted a centre cavity plate;

placing a substrate onto said centre cavity plate;

clamping a top mold, said centre cavity and said bottom mold plates together;

operating a plunger disposed inside said ~~resin~~ pot sleeve to inject said molten resin directly from inside said pot sleeve, through said gates at said discharge end of said pot sleeve into respective mold cavities formed between said centre cavity plate and said substrate; and

after allowing said molten resin to cure after a predetermined time interval, opening both said centre cavity and top mold plates together causes a cull formed on a top face of said plunger to have a reduced volume to reduce wastes and to break off at said mold cavities, and said cull retained by a groove on said top face of said plunger is readily removed by sliding said cull from said groove.

11. A method according to claim 10, wherein said groove has a dovetail or C shape.